

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|--|------------------|---------|---------------------|
| L1 | 2 | "20040061240".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L2 | 3584 | (257/778).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 09:25 |
| L3 | 2 | "20040207084".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L4 | 0 | L3 and substrate with tape | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L5 | 450 | L2 and substrate with tape | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L6 | 333 | L2 and substrate with tape | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L7 | 90 | L6 and underfill | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L8 | 184 | ("4604644" "4825284" "4970575" "4987100" "5107325" "5177669" "5222014" "5239198" "5249101" "5291062" "5311402").PN. OR ("5450283").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L9 | 44 | L2 and surfactant | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L10 | 1 | "6,576,495".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |

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|-----|------|--|------------------------|----|----|------------------|
| L11 | 2728 | tape with substrate with made | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L12 | 743 | L11 and "257"/\$.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L13 | 12 | ("5918364" "5939783" "5985456" "6013417" "6044550" "6165885" "6281046" "6316830" "6319751").PN. OR ("6445075").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L14 | 2 | (US-6445075-\$ or US-6576495-\$ or US-6661104-\$ or US-6724091-\$ or US-6819004-\$).did. | USPAT | OR | ON | 2008/08/18 09:25 |
| L15 | 149 | lead with substrate with bump and 257/778. ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L16 | 6 | ("4624724" "5538771" "5614316" "5670251").PN. OR ("6498400").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L17 | 24 | ("2671844" "3488840" "4661192" "4706811" "4758407" "4806309" "5120678" "5154341" "5269453" "5282565" "5346857" "5352407" "5410184" "5411703" "5527628").PN. OR ("6436730").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L18 | 20 | ("4706811" "4758407" "5120678").PN. OR ("5410184").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L19 | 99 | lead with substrate with bump and 257/738. ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L20 | 99 | lead with substrate with bump and 257/738. ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L21 | 16 | lead with substrate same underfill and 257/738.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |

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| L22 | 5 | lead with substrate same underfill same bump same solder near (resist layer) | USPAT | OR | ON | 2008/08/18 09:25 |
| L23 | 8 | ("5349238" "5442229" "5825081" "6603071" "6744120").PN. OR ("6867490").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L24 | 8 | lead with bump same underfill same bump same solder near (resist layer) | USPAT | OR | ON | 2008/08/18 09:25 |
| L25 | 8 | lead with bump same underfill same solder near (resist layer) | USPAT | OR | ON | 2008/08/18 09:25 |
| L26 | 13347 | lead with bump ssame solder near (resist layer) | USPAT | OR | ON | 2008/08/18 09:25 |
| L27 | 5602 | lead with bump ssame solder near (resist layer) and 257/738.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L28 | 24 | lead with bump same solder near (resist layer) and 257/738.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L29 | 6 | ("4280132" "5953814" "6157085" "6287895").PN. OR ("6710458").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L30 | 44 | ("4604644" "5084961" "5089440" "5121190" "5194930" "5274913" "5400950" "5542601" "5578525" "5615477" "5704116" "5710071").PN. OR ("5953814").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L31 | 1 | "5,656,862".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L32 | 48 | lead with substrate with bump and 257/786.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L33 | 18 | lead with substrate with bump and 257/782.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L34 | 38 | lead with substrate with bump and 257/783.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |

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| L35 | 92 | L32 L33 L34 | USPAT | OR | ON | 2008/08/18 09:25 |
| L36 | 92 | L32 L33 L34 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L37 | 2 | "20040061240".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L38 | 3584 | (257/778).OCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 09:25 |
| L39 | 2 | "20040207084".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L40 | 0 | L39 and substrate with tape | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L41 | 450 | L38 and substrate with tape | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L42 | 333 | L38 and substrate with tape | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L43 | 90 | L42 and underfill | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L44 | 184 | ("4604644" "4825284" "4970575" "4987100" "5107325" "5177669" "5222014" "5239198" "5249101" "5291062" "5311402").PN. OR ("5450283").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L45 | 44 | L38 and surfactant | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |

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| L46 | 1 | "6,576,495".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L47 | 2728 | tape with substrate with made | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L48 | 743 | L47 and "257"/\$.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L49 | 12 | ("5918364" "5939783" "5985456" "6013417" "6044550" "6165885" "6281046" "6316830" "6319751").PN. OR ("6445075").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L50 | 2 | (US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did. | USPAT | OR | ON | 2008/08/18 09:25 |
| L51 | 149 | lead with substrate with bump and 257/778. ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L52 | 6 | ("4624724" "5538771" "5614316" "5670251").PN. OR ("6498400").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L53 | 24 | ("2671844" "3488840" "4661192" "4706811" "4758407" "4806309" "5120678" "5154341" "5269453" "5282565" "5346857" "5352407" "5410184" "5411703" "5527628").PN. OR ("6436730").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L54 | 20 | ("4706811" "4758407" "5120678").PN. OR ("5410184").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L55 | 99 | lead with substrate with bump and 257/738. ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L56 | 99 | lead with substrate with bump and 257/738. ccls. | USPAT | OR | ON | 2008/08/18 09:25 |

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| L57 | 4040 | (257/e23.021).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 09:25 |
| L58 | 2 | L57 and solder with resist same wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L59 | 0 | L57 and solder near2 (resist mask) with underfill with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L60 | 0 | (257/e23.\$4).ccls. and solder near2 (resist mask) with underfill with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L61 | 165 | (257/e23.\$4).ccls. and solder near2 (resist mask) with underfill | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L62 | 156 | (257/e23.\$4).ccls. and solder near2 (resist mask) and pad with underfill | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L63 | 59 | (257/e23.\$4).ccls. and solder near2 (resist mask) same pad with underfill | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L64 | 19 | ("4786545" "5055321" "5278429" "5473512" "5519251" "5756380" "5816478" "5834832" "5872399" "5925403" "6197615" "6286207" "6288451" "6323542" "6344753").PN. OR ("6806560").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L65 | 77758 | (257/e23.\$4).ccls. antirepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |

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| L66 | 0 | (257/e23.\$4).ccls. and antirepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L67 | 0 | (257/e23.\$4).ccls. and antirepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L68 | 0 | (257/e23.\$4).ccls. and nonrepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L69 | 23 | (257/e23.\$4).ccls. and \$5repellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L70 | 1 | (257/e23.\$4).ccls. and anti near2 repellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L71 | 1 | ("257"/\$6).ccls. and anti near2 repellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L72 | 0 | ("257"/\$6).ccls. and solder near2 (resist mask) with underfill with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L73 | 0 | ("257"/\$6).ccls. and solder near2 (resist mask) with underfill\$3 with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L74 | 2 | ("257"/\$6).ccls. and solder near2 (resist mask) with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L75 | 29 | ("257"/\$6).ccls. and solder near2 (resist mask) with (improv\$3, increas\$3) with attach \$5 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |

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| L76 | 4 | ("5703402" "5801440" "6329228").PN. OR ("6608388").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L77 | 20 | ("4706811" "4758407" "5120678").PN. OR ("5410184").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L78 | 24 | ("2671844" "3488840" "4661192" "4706811" "4758407" "4806309" "5120678" "5154341" "5269453" "5282565" "5346857" "5352407" "5410184" "5411703" "5527628").PN. OR ("6436730").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L79 | 2 | "3488840".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L80 | 12 | ("4604644" "5084961" "5089440" "5121190" "5194930" "5274913" "5400950" "5542601" "5578525" "5615477" "5704116" "5710071").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L81 | 129 | ("5710071").URPN. | USPAT | OR | ON | 2008/08/18 09:25 |
| L82 | 5 | "5,71,071".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L83 | 2 | "5710071".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L84 | 2 | "5,710,071".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |

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|-----|------|--|---------------------------|----|----|---------------------|
| L85 | 11 | ("4604644" "5144747" "5182632" "5203076" "5218234" "5296738" "5311059" "5385869" "5473512" "5488200" "5594626").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L86 | 115 | ("4138691" "4268848" "4280132" "4843036" "5001542" "5107325").PN. OR ("5218234").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L87 | 3455 | 257/778.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L88 | 686 | L87 and solder near2 (resist mask) | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L89 | 374 | L88 and polyimide | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L90 | 260 | L88 and polyimide | USPAT | OR | ON | 2008/08/18 09:25 |
| L91 | 29 | ("4658332" "4740414" "4847136" "4847146" "4855872" "4873615" "5026624" "5110867" "5258648" "5262280" "5278010" "5304457" "5329423" "5391435" "5439766" "5439779" "5473119" "5493075" "5496769" "5511306" "5535101" "5579573" "5633535" "5801446" "5808874" "5821305" "5866952" "6002590" "6054250").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L92 | 158 | ("4604644" "4864470" "4931345" "5107325" "5172303" "5241133" "5378869").PN. OR ("5535101").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |

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|------|---------|---|------------------------|----|----|------------------|
| L93 | 1876934 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L94 | 113324 | L93 and "438"/\$.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L95 | 67123 | L93 and "438"/\$.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L96 | 37101 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L97 | 2357 | L96 and "438"/\$.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L98 | 21999 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers | USPAT | OR | ON | 2008/08/18 09:25 |
| L99 | 354333 | L98 and solder ball | USPAT | OR | ON | 2008/08/18 09:25 |
| L100 | 316 | L98 and solder near2 ball | USPAT | OR | ON | 2008/08/18 09:25 |
| L101 | 14 | polyimide near2 substrate with thickness with micrometers | USPAT | OR | ON | 2008/08/18 09:25 |
| L102 | 41 | polyimide near5 substrate with thickness with micrometers | USPAT | OR | ON | 2008/08/18 09:25 |
| L103 | 27 | L102 not L101 | USPAT | OR | ON | 2008/08/18 09:25 |
| L104 | 7 | ("3948429" "4255644" "4300715" "4371912" "4607779" "4638937" "4638938").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L105 | 39 | ("3948429" "4255644" "4300715" "4371912" "4607779" "4638937" "4638938").PN. OR ("5201451").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |

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| L106 | 1062 | thin with polyimide with substrate and "257"/\$.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L107 | 659 | thin with polyimide with substrate and "257"/\$.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L108 | 54 | thin with polyimide with substrate with "mu.m" and "257"/\$.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L109 | 236 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and thin with polyimide with substrate with "mu.m" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L110 | 134 | L109 not "44" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L111 | 184 | L109 not L108 | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L112 | 79 | L109 not L108 | USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L113 | 419 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L114 | 239 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m" | USPAT | OR | ON | 2008/08/18 09:25 |
| L115 | 0 | jp-361633-\$.did. | USPAT | OR | ON | 2008/08/18 09:25 |
| L116 | 0 | jp-361633-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L117 | 1 | jp-1361633-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L118 | 0 | jp-11361633-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |

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|------|----|---|--|----|----|---------------------|
| L119 | 2 | JP-2001176918-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L120 | 20 | ("20010002066" "20010040290" "20010054751" "4263606" "4676864" "4786545" "4963974" "5049718" "5060052" "5132772" "5139610" "5384204" "5844304" "5910685" "6028011" "6175151" "6262488" "6297142").PN. OR ("6518649").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L121 | 18 | ("20010002066" "20010040290" "20010054751" "4263606" "4676864" "4786545" "4963974" "5049718" "5060052" "5132772" "5139610" "5384204" "5844304" "5910685" "6028011" "6175151" "6262488" "6297142").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L122 | 1 | ("6592783").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L123 | 17 | ("4551912" "4811081" "4851964" "4977441" "5032542" "5075252" "5153707" "5232532" "5427641" "5726491" "5949134" "6100112" "6274405" "6313526" "6315156" "6388888" "6559524").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L124 | 7 | ("5260168" "5378581" "5825081" "6313526" "6320135" "6388888" "6433414").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |

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|------|------|---|--|----|-----|---------------------|
| L125 | 18 | ("20010002066" "20010040290" "20010054751" "4263606" "4676864" "4786545" "4963974" "5049718" "5060052" "5132772" "5139610" "5384204" "5844304" "5910685" "6028011" "6175151" "6262488" "6297142").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L126 | 2 | jp-2001176918-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L127 | 2 | "20020043713".pn. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L128 | 1073 | (257/797).OCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 09:25 |
| L129 | 7 | L128 and dummy near2 pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L130 | 15 | L128 and mark with probe | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L131 | 2 | "20040061240".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L132 | 3584 | (257/778).OCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 09:25 |
| L133 | 2 | "20040207084".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |

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|------|------|--|--|----|----|---------------------|
| L134 | 0 | L133 and substrate with tape | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L135 | 450 | L132 and substrate with tape | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L136 | 333 | L132 and substrate with tape | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L137 | 90 | L136 and underfill | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L138 | 184 | ("4604644" "4825284" "4970575" "4987100" "5107325" "5177669" "5222014" "5239198" "5249101" "5291062" "5311402").PN. OR ("5450283").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L139 | 44 | L132 and surfactant | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L140 | 1 | "6,576,495".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L141 | 2728 | tape with substrate with made | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L142 | 743 | L141 and "257"/\$.cls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L143 | 12 | ("5918364" "5939783" "5985456" "6013417" "6044550" "6165885" "6281046" "6316830" "6319751").PN. OR ("6445075").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L144 | 2 | (US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did. | USPAT | OR | ON | 2008/08/18 09:25 |
| L145 | 149 | lead with substrate with bump and 257/778. cls. | USPAT | OR | ON | 2008/08/18 09:25 |

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|------|-------|--|------------------------|----|----|------------------|
| L146 | 6 | ("4624724" "5538771" "5614316" "5670251").PN. OR ("6498400").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L147 | 24 | ("2671844" "3488840" "4661192" "4706811" "4758407" "4806309" "5120678" "5154341" "5269453" "5282565" "5346857" "5352407" "5410184" "5411703" "5527628").PN. OR ("6436730").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L148 | 20 | ("4706811" "4758407" "5120678").PN. OR ("5410184").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L149 | 99 | lead with substrate with bump and 257/738. ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L150 | 99 | lead with substrate with bump and 257/738. ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L151 | 16 | lead with substrate same underfill and 257/738.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L152 | 5 | lead with substrate same underfill same bump same solder near (resist layer) | USPAT | OR | ON | 2008/08/18 09:25 |
| L153 | 8 | ("5349238" "5442229" "5825081" "6603071" "6744120").PN. OR ("6867490").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L154 | 8 | lead with bump same underfill same bump same solder near (resist layer) | USPAT | OR | ON | 2008/08/18 09:25 |
| L155 | 8 | lead with bump same underfill same solder near (resist layer) | USPAT | OR | ON | 2008/08/18 09:25 |
| L156 | 13347 | lead with bump ssame solder near (resist layer) | USPAT | OR | ON | 2008/08/18 09:25 |
| L157 | 5602 | lead with bump ssame solder near (resist layer) and 257/738.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |

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|------|------|--|--|----|-----|---------------------|
| L158 | 24 | lead with bump same solder near (resist layer) and 257/738.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L159 | 6 | ("4280132" "5953814" "6157085" "6287895").PN. OR ("6710458").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L160 | 44 | ("4604644" "5084961" "5089440" "5121190" "5194930" "5274913" "5400950" "5542601" "5578525" "5615477" "5704116" "5710071").PN. OR ("5953814").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L161 | 1 | "5,656,862".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L162 | 48 | lead with substrate with bump and 257/786.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L163 | 18 | lead with substrate with bump and 257/782.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L164 | 38 | lead with substrate with bump and 257/783.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L165 | 92 | L162 L163 L164 | USPAT | OR | ON | 2008/08/18 09:25 |
| L166 | 92 | L162 L163 L164 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L167 | 2 | "20040061240".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L168 | 3584 | (257/778).OCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 09:25 |
| L169 | 2 | "20040207084".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |

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|------|------|--|--|----|----|---------------------|
| L170 | 0 | L169 and substrate with tape | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L171 | 450 | L168 and substrate with tape | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L172 | 333 | L168 and substrate with tape | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L173 | 90 | L172 and underfill | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L174 | 184 | ("4604644" "4825284" "4970575" "4987100" "5107325" "5177669" "5222014" "5239198" "5249101" "5291062" "5311402").PN. OR ("5450283").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L175 | 44 | L168 and surfactant | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L176 | 1 | "6,576,495".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L177 | 2728 | tape with substrate with made | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L178 | 743 | L177 and "257"/\$.cls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L179 | 12 | ("5918364" "5939783" "5985456" "6013417" "6044550" "6165885" "6281046" "6316830" "6319751").PN. OR ("6445075").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L180 | 2 | (US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did. | USPAT | OR | ON | 2008/08/18 09:25 |
| L181 | 149 | lead with substrate with bump and 257/778. cls. | USPAT | OR | ON | 2008/08/18 09:25 |

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| L182 | 6 | ("4624724" "5538771" "5614316" "5670251").PN. OR ("6498400").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L183 | 24 | ("2671844" "3488840" "4661192" "4706811" "4758407" "4806309" "5120678" "5154341" "5269453" "5282565" "5346857" "5352407" "5410184" "5411703" "5527628").PN. OR ("6436730").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L184 | 20 | ("4706811" "4758407" "5120678").PN. OR ("5410184").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L185 | 99 | lead with substrate with bump and 257/738. ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L186 | 99 | lead with substrate with bump and 257/738. ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L187 | 4040 | (257/e23.021).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 09:25 |
| L188 | 2 | L187 and solder with resist same wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L189 | 0 | L187 and solder near2 (resist mask) with underfill with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L190 | 0 | (257/e23.\$4).ccls. and solder near2 (resist mask) with underfill with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L191 | 165 | (257/e23.\$4).ccls. and solder near2 (resist mask) with underfill | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |

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|------|-------|---|--|----|----|---------------------|
| L192 | 156 | (257/e23.\$4).ccls. and solder near2 (resist mask) and pad with underfill | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L193 | 59 | (257/e23.\$4).ccls. and solder near2 (resist mask) same pad with underfill | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L194 | 19 | ("4786545" "5055321" "5278429" "5473512" "5519251" "5756380" "5816478" "5834832" "5872399" "5925403" "6197615" "6286207" "6288451" "6323542" "6344753").PN. OR ("6806560").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L195 | 77758 | (257/e23.\$4).ccls. antirepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L196 | 0 | (257/e23.\$4).ccls. and antirepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L197 | 0 | (257/e23.\$4).ccls. and antirepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L198 | 0 | (257/e23.\$4).ccls. and nonrepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L199 | 23 | (257/e23.\$4).ccls. and \$5repellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L200 | 1 | (257/e23.\$4).ccls. and anti near2 repellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |

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| L201 | 1 | ("257"/\$6).ccls. and anti near2 repellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L202 | 0 | ("257"/\$6).ccls. and solder near2 (resist mask) with underfill with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L203 | 0 | ("257"/\$6).ccls. and solder near2 (resist mask) with underfill\$3 with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L204 | 2 | ("257"/\$6).ccls. and solder near2 (resist mask) with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L205 | 29 | ("257"/\$6).ccls. and solder near2 (resist mask) with (improv\$3, increas\$3) with attach \$5 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L206 | 4 | ("5703402" "5801440" "6329228").PN. OR ("6608388").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L207 | 20 | ("4706811" "4758407" "5120678").PN. OR ("5410184").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L208 | 24 | ("2671844" "3488840" "4661192" "4706811" "4758407" "4806309" "5120678" "5154341" "5269453" "5282565" "5346857" "5352407" "5410184" "5411703" "5527628").PN. OR ("6436730").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L209 | 2 | "3488840".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |

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|------|------|---|--|----|----|---------------------|
| L210 | 12 | ("4604644" "5084961" "5089440" "5121190" "5194930" "5274913" "5400950" "5542601" "5578525" "5615477" "5704116" "5710071").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L211 | 129 | ("5710071").URPN. | USPAT | OR | ON | 2008/08/18 09:25 |
| L212 | 5 | "5,71,071".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L213 | 2 | "5710071".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L214 | 2 | "5,710,071".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L215 | 11 | ("4604644" "5144747" "5182632" "5203076" "5218234" "5296738" "5311059" "5385869" "5473512" "5488200" "5594626").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L216 | 115 | ("4138691" "4268848" "4280132" "4843036" "5001542" "5107325").PN. OR ("5218234").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L217 | 3455 | 257/778.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L218 | 686 | L217 and solder near2 (resist mask) | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L219 | 374 | L218 and polyimide | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L220 | 260 | L218 and polyimide | USPAT | OR | ON | 2008/08/18 09:25 |

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| L221 | 29 | ("4658332" "4740414" "4847136" "4847146" "4855872" "4873615" "5026624" "5110867" "5258648" "5262280" "5278010" "5304457" "5329423" "5391435" "5439766" "5439779" "5473119" "5493075" "5496769" "5511306" "5535101" "5579573" "5633535" "5801446" "5808874" "5821305" "5866952" "6002590" "6054250").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L222 | 158 | ("4604644" "4864470" "4931345" "5107325" "5172303" "5241133" "5378869").PN. OR ("5535101").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L223 | 1876934 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L224 | 113324 | L223 and "438"/\$.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L225 | 67123 | L223 and "438"/\$.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L226 | 37101 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L227 | 2357 | L226 and "438"/\$.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L228 | 21999 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers | USPAT | OR | ON | 2008/08/18 09:25 |

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|------|--------|---|---------------------------|----|----|---------------------|
| L229 | 354333 | L228 and solder ball | USPAT | OR | ON | 2008/08/18 09:25 |
| L230 | 316 | L228 and solder near2 ball | USPAT | OR | ON | 2008/08/18 09:25 |
| L231 | 14 | polyimide near2 substrate with thickness with micrometers | USPAT | OR | ON | 2008/08/18 09:25 |
| L232 | 41 | polyimide near5 substrate with thickness with micrometers | USPAT | OR | ON | 2008/08/18 09:25 |
| L233 | 27 | L232 not L231 | USPAT | OR | ON | 2008/08/18 09:25 |
| L234 | 7 | ("3948429" "4255644" "4300715" "4371912" "4607779" "4638937" "4638938").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L235 | 39 | ("3948429" "4255644" "4300715" "4371912" "4607779" "4638937" "4638938").PN. OR ("5201451").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L236 | 1062 | thin with polyimide with substrate and "257"/\$. ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L237 | 659 | thin with polyimide with substrate and "257"/\$. ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L238 | 54 | thin with polyimide with substrate with "mu.m" and "257"/\$.ccls. | USPAT | OR | ON | 2008/08/18 09:25 |
| L239 | 236 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and thin with polyimide with substrate with "mu.m" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L240 | 134 | L239 not "44" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L241 | 184 | L239 not L238 | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L242 | 79 | L239 not L238 | USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L243 | 419 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |

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| L244 | 239 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m" | USPAT | OR | ON | 2008/08/18 09:25 |
| L245 | 0 | jp-361633-\$.did. | USPAT | OR | ON | 2008/08/18 09:25 |
| L246 | 0 | jp-361633-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L247 | 1 | jp-1361633-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L248 | 0 | jp-11361633-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L249 | 2 | JP-2001176918-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L250 | 20 | ("20010002066" "20010040290" "20010054751" "4263606" "4676864" "4786545" "4963974" "5049718" "5060052" "5132772" "5139610" "5384204" "5844304" "5910685" "6028011" "6175151" "6262488" "6297142").PN. OR ("6518649").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L251 | 18 | ("20010002066" "20010040290" "20010054751" "4263606" "4676864" "4786545" "4963974" "5049718" "5060052" "5132772" "5139610" "5384204" "5844304" "5910685" "6028011" "6175151" "6262488" "6297142").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |

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|------|------|---|--|----|-----|---------------------|
| L252 | 1 | ("6592783").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L253 | 17 | ("4551912" "4811081" "4851964" "4977441" "5032542" "5075252" "5153707" "5232532" "5427641" "5726491" "5949134" "6100112" "6274405" "6313526" "6315156" "6388888" "6559524").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L254 | 7 | ("5260168" "5378581" "5825081" "6313526" "6320135" "6388888" "6433414").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L255 | 18 | ("20010002066" "20010040290" "20010054751" "4263606" "4676864" "4786545" "4963974" "5049718" "5060052" "5132772" "5139610" "5384204" "5844304" "5910685" "6028011" "6175151" "6262488" "6297142").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:25 |
| L256 | 2 | jp-2001176918-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L257 | 2 | "20020043713".pn. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |
| L258 | 1073 | (257/797).OCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 09:25 |
| L259 | 7 | L258 and dummy near2 pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:25 |

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|------|------|--|--|----|-----|---------------------|
| L260 | 15 | L258 and mark with probe | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L261 | 976 | bump with solder with free | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L262 | 976 | bump with solder with free | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L263 | 2 | "20040061240".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L264 | 3584 | (257/778).OCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 09:26 |
| L265 | 2 | "20040207084".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L266 | 0 | L265 and substrate with tape | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L267 | 450 | L264 and substrate with tape | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L268 | 333 | L264 and substrate with tape | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L269 | 90 | L268 and underfill | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L270 | 184 | ("4604644" "4825284" "4970575" "4987100" "5107325" "5177669" "5222014" "5239198" "5249101" "5291062" "5311402").PN. OR ("5450283").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |

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|------|------|---|---------------------------|----|----|---------------------|
| L271 | 44 | L264 and surfactant | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L272 | 1 | "6,576,495".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L273 | 2728 | tape with substrate with made | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L274 | 743 | L273 and "257"/\$.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L275 | 12 | ("5918364" "5939783" "5985456" "6013417" "6044550" "6165885" "6281046" "6316830" "6319751").PN. OR ("6445075").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L276 | 2 | (US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did. | USPAT | OR | ON | 2008/08/18 09:26 |
| L277 | 149 | lead with substrate with bump and 257/778. ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L278 | 6 | ("4624724" "5538771" "5614316" "5670251").PN. OR ("6498400").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L279 | 24 | ("2671844" "3488840" "4661192" "4706811" "4758407" "4806309" "5120678" "5154341" "5269453" "5282565" "5346857" "5352407" "5410184" "5411703" "5527628").PN. OR ("6436730").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L280 | 20 | ("4706811" "4758407" "5120678").PN. OR ("5410184").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L281 | 99 | lead with substrate with bump and 257/738. ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L282 | 99 | lead with substrate with bump and 257/738. ccls. | USPAT | OR | ON | 2008/08/18 09:26 |

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|------|-------|--|------------------------|----|----|------------------|
| L283 | 16 | lead with substrate same underfill and 257/738.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L284 | 5 | lead with substrate same underfill same bump same solder near (resist layer) | USPAT | OR | ON | 2008/08/18 09:26 |
| L285 | 8 | ("5349238" "5442229" "5825081" "6603071" "6744120").PN. OR ("6867490").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L286 | 8 | lead with bump same underfill same bump same solder near (resist layer) | USPAT | OR | ON | 2008/08/18 09:26 |
| L287 | 8 | lead with bump same underfill same solder near (resist layer) | USPAT | OR | ON | 2008/08/18 09:26 |
| L288 | 13347 | lead with bump ssame solder near (resist layer) | USPAT | OR | ON | 2008/08/18 09:26 |
| L289 | 5602 | lead with bump ssame solder near (resist layer) and 257/738.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L290 | 24 | lead with bump same solder near (resist layer) and 257/738.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L291 | 6 | ("4280132" "5953814" "6157085" "6287895").PN. OR ("6710458").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L292 | 44 | ("4604644" "5084961" "5089440" "5121190" "5194930" "5274913" "5400950" "5542601" "5578525" "5615477" "5704116" "5710071").PN. OR ("5953814").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L293 | 1 | "5,656,862".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L294 | 48 | lead with substrate with bump and 257/786.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L295 | 18 | lead with substrate with bump and 257/782.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |

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|------|------|--|--|----|-----|------------------|
| L296 | 38 | lead with substrate with bump and 257/783. ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L297 | 92 | L294 L295 L296 | USPAT | OR | ON | 2008/08/18 09:26 |
| L298 | 92 | L294 L295 L296 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L299 | 2 | "20040061240".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L300 | 3584 | (257/778).OCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 09:26 |
| L301 | 2 | "20040207084".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L302 | 0 | L301 and substrate with tape | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L303 | 450 | L300 and substrate with tape | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L304 | 333 | L300 and substrate with tape | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L305 | 90 | L304 and underfill | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L306 | 184 | ("4604644" "4825284" "4970575" "4987100" "5107325" "5177669" "5222014" "5239198" "5249101" "5291062" "5311402").PN. OR ("5450283").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |

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|------|------|---|---------------------------|----|----|---------------------|
| L307 | 44 | L300 and surfactant | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L308 | 1 | "6,576,495".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L309 | 2728 | tape with substrate with made | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L310 | 743 | L309 and "257"/\$.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L311 | 12 | ("5918364" "5939783" "5985456" "6013417" "6044550" "6165885" "6281046" "6316830" "6319751").PN. OR ("6445075").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L312 | 2 | (US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did. | USPAT | OR | ON | 2008/08/18 09:26 |
| L313 | 149 | lead with substrate with bump and 257/778. ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L314 | 6 | ("4624724" "5538771" "5614316" "5670251").PN. OR ("6498400").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L315 | 24 | ("2671844" "3488840" "4661192" "4706811" "4758407" "4806309" "5120678" "5154341" "5269453" "5282565" "5346857" "5352407" "5410184" "5411703" "5527628").PN. OR ("6436730").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L316 | 20 | ("4706811" "4758407" "5120678").PN. OR ("5410184").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L317 | 99 | lead with substrate with bump and 257/738. ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L318 | 99 | lead with substrate with bump and 257/738. ccls. | USPAT | OR | ON | 2008/08/18 09:26 |

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|------|-------|---|--|----|-----|---------------------|
| L319 | 4040 | (257/e23.021).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 09:26 |
| L320 | 2 | L319 and solder with resist same wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L321 | 0 | L319 and solder near2 (resist mask) with underfill with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L322 | 0 | (257/e23.\$4).ccls. and solder near2 (resist mask) with underfill with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L323 | 165 | (257/e23.\$4).ccls. and solder near2 (resist mask) with underfill | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L324 | 156 | (257/e23.\$4).ccls. and solder near2 (resist mask) and pad with underfill | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L325 | 59 | (257/e23.\$4).ccls. and solder near2 (resist mask) same pad with underfill | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L326 | 19 | ("4786545" "5055321" "5278429" "5473512" "5519251" "5756380" "5816478" "5834832" "5872399" "5925403" "6197615" "6286207" "6288451" "6323542" "6344753").PN. OR ("6806560").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L327 | 77758 | (257/e23.\$4).ccls. antirepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |

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|------|----|---|--|----|----|---------------------|
| L328 | 0 | (257/e23.\$4).ccls. and antirepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L329 | 0 | (257/e23.\$4).ccls. and antirepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L330 | 0 | (257/e23.\$4).ccls. and nonrepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L331 | 23 | (257/e23.\$4).ccls. and \$5repellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L332 | 1 | (257/e23.\$4).ccls. and anti near2 repellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L333 | 1 | ("257"/\$6).ccls. and anti near2 repellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L334 | 0 | ("257"/\$6).ccls. and solder near2 (resist mask) with underfill with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L335 | 0 | ("257"/\$6).ccls. and solder near2 (resist mask) with underfill\$3 with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L336 | 2 | ("257"/\$6).ccls. and solder near2 (resist mask) with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L337 | 29 | ("257"/\$6).ccls. and solder near2 (resist mask) with (improv\$3, increas\$3) with attach \$5 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |

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|------|-----|---|--|----|----|---------------------|
| L338 | 4 | ("5703402" "5801440" "6329228").PN. OR ("6608388").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L339 | 20 | ("4706811" "4758407" "5120678").PN. OR ("5410184").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L340 | 24 | ("2671844" "3488840" "4661192" "4706811" "4758407" "4806309" "5120678" "5154341" "5269453" "5282565" "5346857" "5352407" "5410184" "5411703" "5527628").PN. OR ("6436730").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L341 | 2 | "3488840".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L342 | 12 | ("4604644" "5084961" "5089440" "5121190" "5194930" "5274913" "5400950" "5542601" "5578525" "5615477" "5704116" "5710071").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L343 | 129 | ("5710071").URPN. | USPAT | OR | ON | 2008/08/18 09:26 |
| L344 | 5 | "5,71,071".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L345 | 2 | "5710071".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L346 | 2 | "5,710,071".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |

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|------|------|--|---------------------------|----|----|---------------------|
| L347 | 11 | ("4604644" "5144747" "5182632" "5203076" "5218234" "5296738" "5311059" "5385869" "5473512" "5488200" "5594626").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L348 | 115 | ("4138691" "4268848" "4280132" "4843036" "5001542" "5107325").PN. OR ("5218234").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L349 | 3455 | 257/778.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L350 | 686 | L349 and solder near2 (resist mask) | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L351 | 374 | L350 and polyimide | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L352 | 260 | L350 and polyimide | USPAT | OR | ON | 2008/08/18 09:26 |
| L353 | 29 | ("4658332" "4740414" "4847136" "4847146" "4855872" "4873615" "5026624" "5110867" "5258648" "5262280" "5278010" "5304457" "5329423" "5391435" "5439766" "5439779" "5473119" "5493075" "5496769" "5511306" "5535101" "5579573" "5633535" "5801446" "5808874" "5821305" "5866952" "6002590" "6054250").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L354 | 158 | ("4604644" "4864470" "4931345" "5107325" "5172303" "5241133" "5378869").PN. OR ("5535101").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |

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|------|---------|---|------------------------|----|----|------------------|
| L355 | 1876934 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L356 | 113324 | L355 and "438"/\$.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L357 | 67123 | L355 and "438"/\$.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L358 | 37101 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L359 | 2357 | L358 and "438"/\$.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L360 | 21999 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers | USPAT | OR | ON | 2008/08/18 09:26 |
| L361 | 354333 | L360 and solder ball | USPAT | OR | ON | 2008/08/18 09:26 |
| L362 | 316 | L360 and solder near2 ball | USPAT | OR | ON | 2008/08/18 09:26 |
| L363 | 14 | polyimide near2 substrate with thickness with micrometers | USPAT | OR | ON | 2008/08/18 09:26 |
| L364 | 41 | polyimide near5 substrate with thickness with micrometers | USPAT | OR | ON | 2008/08/18 09:26 |
| L365 | 27 | L364 not L363 | USPAT | OR | ON | 2008/08/18 09:26 |
| L366 | 7 | ("3948429" "4255644" "4300715" "4371912" "4607779" "4638937" "4638938").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L367 | 39 | ("3948429" "4255644" "4300715" "4371912" "4607779" "4638937" "4638938").PN. OR ("5201451").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |

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|------|------|---|--|----|----|------------------|
| L368 | 1062 | thin with polyimide with substrate and "257"/\$.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L369 | 659 | thin with polyimide with substrate and "257"/\$.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L370 | 54 | thin with polyimide with substrate with "mu.m" and "257"/\$.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L371 | 236 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and thin with polyimide with substrate with "mu.m" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L372 | 134 | L371 not "44" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L373 | 184 | L371 not L370 | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L374 | 79 | L371 not L370 | USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L375 | 419 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L376 | 239 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m" | USPAT | OR | ON | 2008/08/18 09:26 |
| L377 | 0 | jp-361633-\$.did. | USPAT | OR | ON | 2008/08/18 09:26 |
| L378 | 0 | jp-361633-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L379 | 1 | jp-1361633-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L380 | 0 | jp-11361633-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |

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|------|----|---|--|----|----|---------------------|
| L381 | 2 | JP-2001176918-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L382 | 20 | ("20010002066" "20010040290" "20010054751" "4263606" "4676864" "4786545" "4963974" "5049718" "5060052" "5132772" "5139610" "5384204" "5844304" "5910685" "6028011" "6175151" "6262488" "6297142").PN. OR ("6518649").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L383 | 18 | ("20010002066" "20010040290" "20010054751" "4263606" "4676864" "4786545" "4963974" "5049718" "5060052" "5132772" "5139610" "5384204" "5844304" "5910685" "6028011" "6175151" "6262488" "6297142").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L384 | 1 | ("6592783").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L385 | 17 | ("4551912" "4811081" "4851964" "4977441" "5032542" "5075252" "5153707" "5232532" "5427641" "5726491" "5949134" "6100112" "6274405" "6313526" "6315156" "6388888" "6559524").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L386 | 7 | ("5260168" "5378581" "5825081" "6313526" "6320135" "6388888" "6433414").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |

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|------|------|---|--|----|-----|---------------------|
| L387 | 18 | ("20010002066" "20010040290" "20010054751" "4263606" "4676864" "4786545" "4963974" "5049718" "5060052" "5132772" "5139610" "5384204" "5844304" "5910685" "6028011" "6175151" "6262488" "6297142").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L388 | 2 | jp-2001176918-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L389 | 2 | "20020043713".pn. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L390 | 1073 | (257/797).OCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 09:26 |
| L391 | 7 | L390 and dummy near2 pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L392 | 15 | L390 and mark with probe | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L393 | 2 | "20040061240".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L394 | 3584 | (257/778).OCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 09:26 |
| L395 | 2 | "20040207084".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |

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|------|------|--|--|----|----|---------------------|
| L396 | 0 | L395 and substrate with tape | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L397 | 450 | L394 and substrate with tape | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L398 | 333 | L394 and substrate with tape | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L399 | 90 | L398 and underfill | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L400 | 184 | ("4604644" "4825284" "4970575" "4987100" "5107325" "5177669" "5222014" "5239198" "5249101" "5291062" "5311402").PN. OR ("5450283").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L401 | 44 | L394 and surfactant | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L402 | 1 | "6,576,495".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L403 | 2728 | tape with substrate with made | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L404 | 743 | L403 and "257"/\$.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L405 | 12 | ("5918364" "5939783" "5985456" "6013417" "6044550" "6165885" "6281046" "6316830" "6319751").PN. OR ("6445075").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L406 | 2 | (US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did. | USPAT | OR | ON | 2008/08/18 09:26 |
| L407 | 149 | lead with substrate with bump and 257/778. ccls. | USPAT | OR | ON | 2008/08/18 09:26 |

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|------|-------|---|---------------------------|----|----|---------------------|
| L408 | 6 | ("4624724" "5538771" "5614316" "5670251").PN. OR ("6498400").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L409 | 24 | ("2671844" "3488840" "4661192" "4706811" "4758407" "4806309" "5120678" "5154341" "5269453" "5282565" "5346857" "5352407" "5410184" "5411703" "5527628").PN. OR ("6436730").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L410 | 20 | ("4706811" "4758407" "5120678").PN. OR ("5410184").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L411 | 99 | lead with substrate with bump and 257/738. ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L412 | 99 | lead with substrate with bump and 257/738. ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L413 | 16 | lead with substrate same underfill and 257/738.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L414 | 5 | lead with substrate same underfill same bump same solder near (resist layer) | USPAT | OR | ON | 2008/08/18 09:26 |
| L415 | 8 | ("5349238" "5442229" "5825081" "6603071" "6744120").PN. OR ("6867490").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L416 | 8 | lead with bump same underfill same bump same solder near (resist layer) | USPAT | OR | ON | 2008/08/18 09:26 |
| L417 | 8 | lead with bump same underfill same solder near (resist layer) | USPAT | OR | ON | 2008/08/18 09:26 |
| L418 | 13347 | lead with bump ssame solder near (resist layer) | USPAT | OR | ON | 2008/08/18 09:26 |
| L419 | 5602 | lead with bump ssame solder near (resist layer) and 257/738.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |

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|------|------|--|--|----|-----|------------------|
| L420 | 24 | lead with bump same solder near (resist layer) and 257/738.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L421 | 6 | ("4280132" "5953814" "6157085" "6287895").PN. OR ("6710458").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L422 | 44 | ("4604644" "5084961" "5089440" "5121190" "5194930" "5274913" "5400950" "5542601" "5578525" "5615477" "5704116" "5710071").PN. OR ("5953814").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L423 | 1 | "5,656,862".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L424 | 48 | lead with substrate with bump and 257/786.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L425 | 18 | lead with substrate with bump and 257/782.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L426 | 38 | lead with substrate with bump and 257/783.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L427 | 92 | L424 L425 L426 | USPAT | OR | ON | 2008/08/18 09:26 |
| L428 | 92 | L424 L425 L426 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L429 | 2 | "20040061240".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L430 | 3584 | (257/778).OCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 09:26 |
| L431 | 2 | "20040207084".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |

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|------|------|--|--|----|----|---------------------|
| L432 | 0 | L431 and substrate with tape | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L433 | 450 | L430 and substrate with tape | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L434 | 333 | L430 and substrate with tape | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L435 | 90 | L434 and underfill | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L436 | 184 | ("4604644" "4825284" "4970575" "4987100" "5107325" "5177669" "5222014" "5239198" "5249101" "5291062" "5311402").PN. OR ("5450283").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L437 | 44 | L430 and surfactant | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L438 | 1 | "6,576,495".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L439 | 2728 | tape with substrate with made | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L440 | 743 | L439 and "257"/\$.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L441 | 12 | ("5918364" "5939783" "5985456" "6013417" "6044550" "6165885" "6281046" "6316830" "6319751").PN. OR ("6445075").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L442 | 2 | (US-6445075-\$ or US- 6576495-\$ or US- 6661104-\$ or US- 6724091-\$ or US- 6819004-\$).did. | USPAT | OR | ON | 2008/08/18 09:26 |
| L443 | 149 | lead with substrate with bump and 257/778. ccls. | USPAT | OR | ON | 2008/08/18 09:26 |

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|------|------|---|--|----|-----|---------------------|
| L444 | 6 | ("4624724" "5538771" "5614316" "5670251").PN. OR ("6498400").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L445 | 24 | ("2671844" "3488840" "4661192" "4706811" "4758407" "4806309" "5120678" "5154341" "5269453" "5282565" "5346857" "5352407" "5410184" "5411703" "5527628").PN. OR ("6436730").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L446 | 20 | ("4706811" "4758407" "5120678").PN. OR ("5410184").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L447 | 99 | lead with substrate with bump and 257/738. ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L448 | 99 | lead with substrate with bump and 257/738. ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L449 | 4040 | (257/e23.021).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 09:26 |
| L450 | 2 | L449 and solder with resist same wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L451 | 0 | L449 and solder near2 (resist mask) with underfill with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L452 | 0 | (257/e23.\$4).ccls. and solder near2 (resist mask) with underfill with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L453 | 165 | (257/e23.\$4).ccls. and solder near2 (resist mask) with underfill | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |

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|------|-------|---|--|----|----|---------------------|
| L454 | 156 | (257/e23.\$4).ccls. and solder near2 (resist mask) and pad with underfill | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L455 | 59 | (257/e23.\$4).ccls. and solder near2 (resist mask) same pad with underfill | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L456 | 19 | ("4786545" "5055321" "5278429" "5473512" "5519251" "5756380" "5816478" "5834832" "5872399" "5925403" "6197615" "6286207" "6288451" "6323542" "6344753").PN. OR ("6806560").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L457 | 77758 | (257/e23.\$4).ccls. antirepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L458 | 0 | (257/e23.\$4).ccls. and antirepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L459 | 0 | (257/e23.\$4).ccls. and antirepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L460 | 0 | (257/e23.\$4).ccls. and nonrepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L461 | 23 | (257/e23.\$4).ccls. and \$5repellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L462 | 1 | (257/e23.\$4).ccls. and anti near2 repellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |

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|------|----|--|--|----|----|---------------------|
| L463 | 1 | ("257"/\$6).ccls. and anti near2 repellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L464 | 0 | ("257"/\$6).ccls. and solder near2 (resist mask) with underfill with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L465 | 0 | ("257"/\$6).ccls. and solder near2 (resist mask) with underfill\$3 with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L466 | 2 | ("257"/\$6).ccls. and solder near2 (resist mask) with wetab\$6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L467 | 29 | ("257"/\$6).ccls. and solder near2 (resist mask) with (improv\$3, increas\$3) with attach \$5 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L468 | 4 | ("5703402" "5801440" "6329228").PN. OR ("6608388").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L469 | 20 | ("4706811" "4758407" "5120678").PN. OR ("5410184").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L470 | 24 | ("2671844" "3488840" "4661192" "4706811" "4758407" "4806309" "5120678" "5154341" "5269453" "5282565" "5346857" "5352407" "5410184" "5411703" "5527628").PN. OR ("6436730").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L471 | 2 | "3488840".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |

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|------|------|---|--|----|----|---------------------|
| L472 | 12 | ("4604644" "5084961" "5089440" "5121190" "5194930" "5274913" "5400950" "5542601" "5578525" "5615477" "5704116" "5710071").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L473 | 129 | ("5710071").URPN. | USPAT | OR | ON | 2008/08/18 09:26 |
| L474 | 5 | "5,71,071".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L475 | 2 | "5710071".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L476 | 2 | "5,710,071".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L477 | 11 | ("4604644" "5144747" "5182632" "5203076" "5218234" "5296738" "5311059" "5385869" "5473512" "5488200" "5594626").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L478 | 115 | ("4138691" "4268848" "4280132" "4843036" "5001542" "5107325").PN. OR ("5218234").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L479 | 3455 | 257/778.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L480 | 686 | L479 and solder near2 (resist mask) | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L481 | 374 | L480 and polyimide | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L482 | 260 | L480 and polyimide | USPAT | OR | ON | 2008/08/18 09:26 |

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|------|---------|--|---------------------------|----|----|---------------------|
| L483 | 29 | ("4658332" "4740414" "4847136" "4847146" "4855872" "4873615" "5026624" "5110867" "5258648" "5262280" "5278010" "5304457" "5329423" "5391435" "5439766" "5439779" "5473119" "5493075" "5496769" "5511306" "5535101" "5579573" "5633535" "5801446" "5808874" "5821305" "5866952" "6002590" "6054250").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L484 | 158 | ("4604644" "4864470" "4931345" "5107325" "5172303" "5241133" "5378869").PN. OR ("5535101").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L485 | 1876934 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L486 | 113324 | L485 and "438"/\$.ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L487 | 67123 | L485 and "438"/\$.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L488 | 37101 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L489 | 2357 | L488 and "438"/\$.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L490 | 21999 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide near3 substrate thickness with micrometers | USPAT | OR | ON | 2008/08/18 09:26 |

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|------|--------|--|---------------------------|----|----|---------------------|
| L491 | 354333 | L490 and solder ball | USPAT | OR | ON | 2008/08/18 09:26 |
| L492 | 316 | L490 and solder near2 ball | USPAT | OR | ON | 2008/08/18 09:26 |
| L493 | 14 | polyimide near2 substrate with thickness with micrometers | USPAT | OR | ON | 2008/08/18 09:26 |
| L494 | 41 | polyimide near5 substrate with thickness with micrometers | USPAT | OR | ON | 2008/08/18 09:26 |
| L495 | 27 | L494 not L493 | USPAT | OR | ON | 2008/08/18 09:26 |
| L496 | 7 | ("3948429" "4255644" "4300715" "4371912" "4607779" "4638937" "4638938").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L497 | 39 | ("3948429" "4255644" "4300715" "4371912" "4607779" "4638937" "4638938").PN. OR ("5201451").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L498 | 1062 | thin with polyimide with substrate and "257"/\$. ccls. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L499 | 659 | thin with polyimide with substrate and "257"/\$. ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L500 | 54 | thin with polyimide with substrate with "mu.m" and "257"/\$.ccls. | USPAT | OR | ON | 2008/08/18 09:26 |
| L501 | 236 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and thin with polyimide with substrate with "mu.m" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L502 | 134 | L501 not "44" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L503 | 184 | L501 not L500 | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L504 | 79 | L501 not L500 | USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L505 | 419 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m" | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |

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|------|-----|--|--|----|----|------------------|
| L506 | 239 | (IC integrated near1 circuit chip die semiconductor silicon wafer) and polyimide with tape with "mu.m" | USPAT | OR | ON | 2008/08/18 09:26 |
| L507 | 0 | jp-361633-\$.did. | USPAT | OR | ON | 2008/08/18 09:26 |
| L508 | 0 | jp-361633-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L509 | 1 | jp-1361633-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L510 | 0 | jp-11361633-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L511 | 2 | JP-2001176918-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L512 | 20 | ("20010002066" "20010040290" "20010054751" "4263606" "4676864" "4786545" "4963974" "5049718" "5060052" "5132772" "5139610" "5384204" "5844304" "5910685" "6028011" "6175151" "6262488" "6297142").PN. OR ("6518649").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L513 | 18 | ("20010002066" "20010040290" "20010054751" "4263606" "4676864" "4786545" "4963974" "5049718" "5060052" "5132772" "5139610" "5384204" "5844304" "5910685" "6028011" "6175151" "6262488" "6297142").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |

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|------|------|---|--|----|-----|---------------------|
| L514 | 1 | ("6592783").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L515 | 17 | ("4551912" "4811081" "4851964" "4977441" "5032542" "5075252" "5153707" "5232532" "5427641" "5726491" "5949134" "6100112" "6274405" "6313526" "6315156" "6388888" "6559524").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L516 | 7 | ("5260168" "5378581" "5825081" "6313526" "6320135" "6388888" "6433414").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L517 | 18 | ("20010002066" "20010040290" "20010054751" "4263606" "4676864" "4786545" "4963974" "5049718" "5060052" "5132772" "5139610" "5384204" "5844304" "5910685" "6028011" "6175151" "6262488" "6297142").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2008/08/18 09:26 |
| L518 | 2 | jp-2001176918-\$.did. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L519 | 2 | "20020043713".pn. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L520 | 1073 | (257/797).OCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 09:26 |
| L521 | 7 | L520 and dummy near2 pad | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |

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|------|------|---|--|----|-----|---------------------|
| L522 | 15 | L520 and mark with probe | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 09:26 |
| L523 | 780 | (257/684).OCLS. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 10:04 |
| L524 | 1473 | (257/701).OCLS. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 10:04 |
| L525 | 965 | (257/782).OCLS. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2008/08/18 10:04 |
| L526 | 3135 | I523 I524 I525 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 10:05 |
| L527 | 0 | 526 and antirepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 10:05 |
| L528 | 0 | I526 and antirepellant | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2008/08/18 10:06 |
| L529 | 101 | ((bump solder projection electrode ball) and (semiconductor chip die IC integrated adj circuit wafer silicon micro \$3device) and (anti \$repellent repellent)). clm. | US-PGPUB | OR | ON | 2008/08/18 10:09 |

8/18/2008 10:12:09 AM

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